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J.M. Baunson  
10/11/01



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Thomas P. Glenn, Steven Webster, Markus K. Liebhard  
Assignee: Amkor Technology, Inc.  
Title: CHIP SIZE IMAGE SENSOR WIREBOND PACKAGE FABRICATION METHOD  
Serial No.: 09/712,314 Filed: November 13, 2000  
Examiner: Unknown Group Art Unit: 2878  
Docket No.: G0026M

Monterey, CA  
September 25, 2001

ASSISTANT COMMISSIONER FOR PATENTS  
ATTN: Official Draftsperson  
Washington, D.C. 20231

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SUBMISSION OF FORMAL DRAWINGS

Dear Sir:

Applicants submit eight (8) sheets of formal drawings consisting of Figures 1, 2, 3, 4, 5, 6, 7A, 7B, 7C, 7D, 7E, 8A, 8B, 9, 10, 11, 12, 13 and 14. If there are any questions concerning the formal drawings, please call the undersigned at the number given.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on September 25, 2001.

\_\_\_\_\_  
Attorney for Applicant(s)

September 25, 2001  
\_\_\_\_\_  
Date of Signature

Respectfully submitted,

Serge J. Hodgson  
Attorney for Applicant(s)  
Reg. No. 40,017  
(831) 655-0880 Ext. 12